

Marked Up Version

In the Claims

1. (Once Amended) A printed wiring board comprising an odd number n of conductive layers which are built up [via] with an odd number of insulating layers respectively and are electrically connected to one another [via] by interconnecting through holes;

wherein the first conductive layer is a component-connecting layer on which an electronic component is to be mounted and [leads] conducts electric currents in and out of the electronic component; the n -th conductive layer is an external connecting layer for connecting external connecting terminals which [leads] conducts electric currents in and out of the printed wiring board; the second to $(n-1)$ -th conductive layers are current transmitting layers for transmitting internal currents of the printed wiring board; and the surface of the n -th conductive layer is covered with the n -th and outermost insulating layer with external connecting terminals being exposed, and wherein a central insulating layer of the odd number of insulating layers prevents warping from occurring in the printed wiring board.

3. (Twice Amended) A method of manufacturing a printed wiring board having an odd number n of conductive layers which are built up [via] with an odd number of insulating layers respectively and are electrically connected to one another [via] by interconnecting through holes, the method comprising the steps of:

interposing insulating layers between the second to n -th conductive layers respectively and also forming first interconnecting through holes for electrically connecting the conductive layers to one another;

laminating a first prepreg and a copper foil on a surface of the second conductive layer, and press-bonding a second prepreg on a surface of the n-th conductive layer to form a multilayer substrate having an odd number n of insulating layers, wherein the second to n-th conductive layers are internal layers of the multilayer substrate;

etching the copper foil to form a first conductive layer;

forming second interconnecting through holes in the first insulating layer and forming connecting holes in the n-th insulating layer respectively;

forming a metal plating film for electrically connecting the first conductive layer with the second conductive layer on the walls of the second interconnecting through holes of the first insulating layer; and

connecting external connecting terminals to the surface of the n-th conductive layer exposed through the connecting holes of the n-th insulating layer.

4. (Amended) A printed wiring board comprising an internal insulating substrate having a conductor circuit formed on a surface thereof, [at least one] an internal insulating layer laminated on the surface of the internal insulating substrate, and an external insulating layer laminated on a surface of the internal insulating layer, the internal insulating layer and the external insulating layer having an internal conductor circuit and an external conductor circuit respectively;

wherein the internal insulating layer comprises two or more internal insulating layers of glass cloth-reinforced prepreg.

Marked Up Version of Abstract

In a printed wiring board, an odd number (n) of conductive layers (11-13) and insulating layers (21-23) are alternately laminated upon [another] each other. The first conductive layer (11) is [constituted as] a parts connecting layer and the n -th conductive layer (13) is [constituted as] an external connecting layer which is connected to external connecting terminals (7). The second to $(n-1)$ -th conductive layers (12) are [constituted as] current transmitting layers for transmitting internal currents. The surface of the n -th insulating layer (23) is in a state where the external connecting terminals (7) are exposed on the surface. It is preferable to [constitute] make the initial insulating layers of a glass-cloth reinforced prepreg and the external insulating layers of a resin.

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